



Material Content Data Sheet



Sales Product Name		BSZ180P03NS3 G		Issued		27. September 2017		
MA#		MA001407814						
Package		PG-TSDSON-8-1		Weight*		36.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.936	2.59	2.59	25851	25851
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		262	
	non noble metal	iron	7439-89-6	0.189	0.52		5231	
wire	non noble metal	copper	7440-50-8	7.689	21.24	21.80	212406	217964
	non noble metal	copper	7440-50-8	0.053	0.15	0.15	1454	1454
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1023
encapsulation	plastics	epoxy resin	-	1.908	5.27		52699	
	inorganic material	silicondioxide	60676-86-0	16.576	45.79	51.16	457920	511642
leadfinish	non noble metal	tin	7440-31-5	0.375	1.04	1.04	10351	10351
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2232	2232
solder	noble metal	silver	7440-22-4	0.029	0.08		803	
	non noble metal	tin	7440-31-5	0.023	0.06		643	
	non noble metal	lead	7439-92-1	1.111	3.07	3.21	30690	32136
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2596	
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.54	10.81	105415	108173
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
heat sink CLIP	non noble metal	iron	7439-89-6	0.078	0.22		2165	
	non noble metal	copper	7440-50-8	3.182	8.79	9.02	87897	90197
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com